# **PECL\* to TTL Translator**

(+5 Vdc Power Supply Only)

#### **Description**

The MC10H350 is a member of the 10H family of high performance ECL logic. It consists of 4 translators with differential inputs and TTL outputs. The 3-state outputs can be disabled by applying a HIGH TTL logic level on the common OE input.

The MC10H350 is designed to be used primarily in systems incorporating both ECL and TTL logic operating off a common power supply. The separate V<sub>CC</sub> power pins are not connected internally and thus isolate the noisy TTL V<sub>CC</sub> runs from the relatively quiet ECL V<sub>CC</sub> runs on the printed circuit board. The differential inputs allow the MC10H350 to be used as an inverting or noninverting translator, or a differential line receiver. The MC10H350 can also drive CMOS with the addition of a pullup resistor.

#### **Features**

- Propagation Delay, 3.5 ns Typical
- MECL 10K<sup>TM</sup> Compatible
- Pb-Free Packages are Available\*



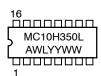
# ON Semiconductor®

http://onsemi.com

#### **MARKING DIAGRAMS\***







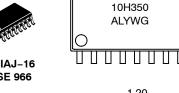
MC10H350P **AWLYYWWG** 



PDIP-16 P SUFFIX **CASE 648** 



SOEIAJ-16 **CASE 966** 





PLLC-20 **FN SUFFIX CASE 775** 



= Assembly Location WL, L = Wafer Lot YY, Y = Year WW, W = Work Week = Pb-Free Package

Application Note AND8002/D.

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

<sup>\*</sup>For additional marking information, refer to

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**ORDERING INFORMATION** 

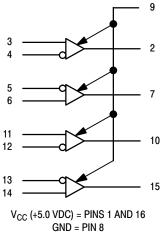
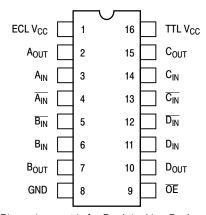


Figure 1. Logic Diagram



Pin assignment is for Dual-in-Line Package.

Figure 2. Dip Pin Assignment

**Table 1. MAXIMUM RATINGS** 

Symbol	Characteristic	Rating	Unit
V <sub>CC</sub>	Power Supply (V <sub>EE</sub> = GND)	7.0	Vdc
T <sub>A</sub>	Operating Temperature Range	0 to +75	°C
T <sub>stg</sub>	Storage Temperature Range - Plastic - Ceramic	-55 to +150 -55 to +165	°C °C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS ( $V_{CC}$  = 5.0 V  $\pm$ 5%) (Note 1)

			T <sub>A</sub> = 0°C	C to 75°C	
Symbol	Characteristic		Min	Max	Unit
I <sub>CC</sub>	Power Supply Current	TTL	-	20	mA
		ECL	-	12	
I <sub>IH</sub>	Input Current High	Pin 9	-	20	μΑ
I <sub>INH</sub>		Others	-	50	
$I_{IL}$	Input Current Low	Pin 9	-	-0.6	mA
I <sub>INL</sub>		Others	-	50	μΑ
V <sub>IH</sub>	Input Voltage High	Pin 9	2.0	-	Vdc
V <sub>IL</sub>	Input Voltage Low	Pin 9	-	0.8	Vdc
V <sub>DIFF</sub>	Differential Input Voltage (Note 1)		350	-	mV
	Pins 3–6, 11–14 (1)				
$V_{CM}$	Voltage Common Mode		2.8	$V_{CC}$	Vdc
	Pins 3–6, 11–14				
V <sub>OH</sub>	Output Voltage High		2.7	_	Vdc
	I <sub>OH</sub> = 3.0 mA				
V <sub>OL</sub>	Output Voltage Low		-	0.5	Vdc
	I <sub>OL</sub> = 20 mA				
Ios	Short Circuit Current		-60	-150	mA
	V <sub>OUT</sub> = 0 V				
I <sub>OZH</sub>	Output Disable Current High		-	50	μΑ
	V <sub>OUT</sub> = 2.7 V				
I <sub>OZL</sub>	Output Disable Current Low		-	-50	μΑ
	V <sub>OUT</sub> = 0.5 V				

<sup>\*</sup>Positive Emitter Coupled Logic

Table 3. AC PARAMETERS ( $C_L = 50 \text{ pF}$ ) ( $V_{CC} = 5.0 \pm 5\%$ ) ( $T_A = 0^{\circ}\text{C}$  to  $75^{\circ}\text{C}$ )

		T <sub>A</sub> = 0°C to 75°C		
Symbol	Characteristic	Min	Max	Unit
t <sub>pd</sub>	Propagation Delay Data (50% to 1.5 V)	1.5	5.0	ns
t <sub>r</sub>	Rise Time (Note 4)	0.3	1.6	ns
t <sub>f</sub>	Fall Time (Note 4)	0.3	1.6	ns
t <sub>pdLZ</sub> t <sub>pdHZ</sub>	Output Disable Time	2.0 2.0	6.0 6.0	ns
t <sub>pdZL</sub> t <sub>pdZH</sub>	Output Enable Time	2.0 2.0	8.0 8.0	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. 1.0 V to 2.0 V w/50 pF into 500  $\Omega$ .

<sup>1.</sup> Common mode input voltage to pins 3-4, 5-6, 11-12, 13-14 must be between the values of 2.8 V and 5.0 V. This common mode input voltage range includes the differential input swing.

For single-ended use, apply 3.75 V (V<sub>BB</sub>) to either input depending on output polarity required. Signal level range to other input is 3.3 V to 4.2 V.
 Any unused gates should have the inverting inputs tied to V<sub>CC</sub> and the noninverting inputs tied to ground to prevent output glitching.

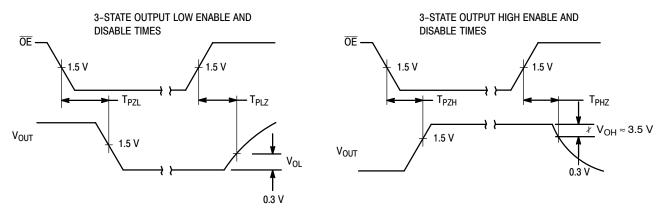
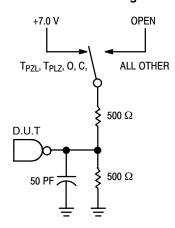


Figure 3. 3-State Switching Waveforms



\*INCLUDES JIG AND PROBE CAPACITANCE

Application Note: Pin 9 is an  $\overline{OE}$  and the MC10H350 is disabled when  $\overline{OE}$  is at  $V_{IH}$  or higher.

Figure 4. Test Load

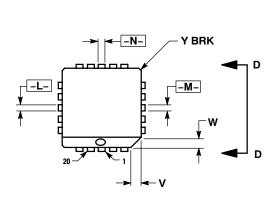
#### **ORDERING INFORMATION**

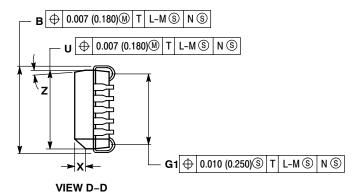
Device	Package	Shipping <sup>†</sup>	
MC10H350FN	PLLC-20	46 Units / Rail	
MC10H350FNG	PLLC-20 (Pb-Free)	46 Units / Rail	
MC10H350FNR2	PLLC-20	500 / Tape & Reel	
MC10H350FNR2G	PLLC-20 (Pb-Free)	500 / Tape & Reel	
MC10H350L	CDIP-16	25 Unit / Rail	
MC10H350M	SOEIAJ-16	50 Unit / Rail	
MC10H350MG	SOEIAJ-16 (Pb-Free)	50 Unit / Rail	
MC10H350MEL	SOEIAJ-16	2000 / Tape & Reel	
MC10H350MELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel	
MC10H350P	PDIP-16	25 Unit / Rail	
MC10H350PG	PDIP-16 (Pb-Free)	25 Unit / Rail	

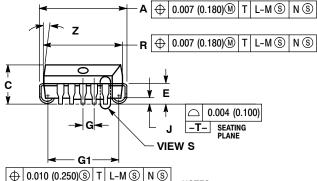
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

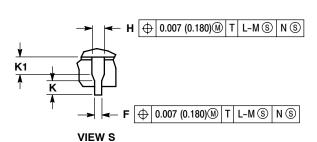
#### PACKAGE DIMENSIONS

#### **20 LEAD PLLC** CASE 775-02 **ISSUE E**









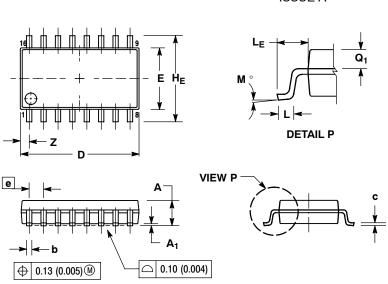
- NOTES:
  1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. DIMENSIONS IN INCHES.
  3. DATUMS -L., -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

- PARTING LINE.
  4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM —T-, SEATING PLANE.
  5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
  6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- PLASTIC BODY.
  7. DIMENSION H DOES NOT INCLUDE DAMBAR DIMIENSION H DUES NOT INCLUDE DAMBAR
  PROTRUSION OR INTRUSION. THE DAMBAR
  PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION
  TO BE GREATER THAN 0.037 (0.940). THE DAMBAR
  INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO
  BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Е	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
c	0.350	0.356	8.89	9.04	
٧	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Х	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10°	2°	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

#### PACKAGE DIMENSIONS

#### SOEIAJ-16 CASE 966-01 **ISSUE A**



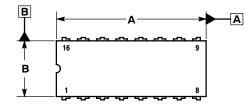
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI

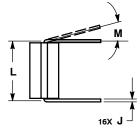
- NOTES:

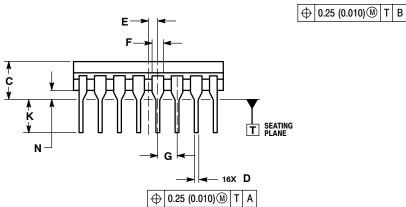
  1 DIMENSIONING AND TOLERANCING PER ANSI
  Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSIONS DI AND E DO NOT INCLUDE MOLD
  FLASH OR PROTRUSIONS AND ARE MEASURED
  AT THE PARTING LINE. MOLD FLASH OR
  PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006)
  PER SIDE.
  4. TERMINAL NUMBERS ARE SHOWN FOR
  REFERENCE ONLY.
  5. THE LEAD WIDTH DIMENSION (b) DOES NOT
  INCLUDE DAMBAR PROTRUSION. ALLOWABLE
  DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
  TOTAL IN EXCESS OF THE LEAD WIDTH
  DIMENSION AT MAXIMUM MATERIAL CONDITION.
  DAMBAR CANNOT BE LOCATED ON THE LOWER
  RADIUS OR THE FOOT. MINIMUM SPACE
  BETWEEN PROTRUSIONS AND ADJACENT LEAD
  TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
Q <sub>1</sub>	0.70	0.90	0.028	0.035
Z		0.78		0.031

### CDIP-16 **L SUFFIX** CERAMIC DIP PACKAGE CASE 620A-01 **ISSUE O**







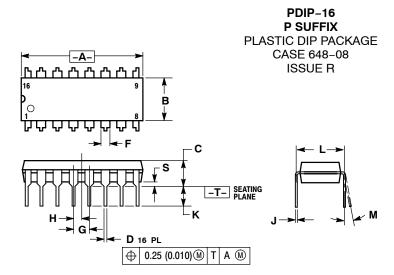
#### NOTES:

- DIMENSIONING AND TOLERANCING PER

- DIMENSIONING AND TOLEHARICING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: INCH.
  DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  DIMENSION F MAY NARROW TO 0.76 (0.030)
  WHERE THE LEAD ENTERS THE CERAMIC BODY.
  THIS DRAWING REPLACES OBSOLETE
- CASE OUTLINE 620-10.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.750	0.785	19.05	19.93
В	0.240	0.295	6.10	7.49
C		0.200		5.08
D	0.015	0.020	0.39	0.50
Е	0.050	BSC	1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100	BSC	2.54 BSC	
Н	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0 °	15°	0 °	15°
N	0.020	0.040	0.51	1.01

#### PACKAGE DIMENSIONS



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  ROUNDED CORNERS OPTIONAL.

	INCHES		IES MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
Н	0.050 BSC		1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10 °
S	0.020	0.040	0.51	1.01

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